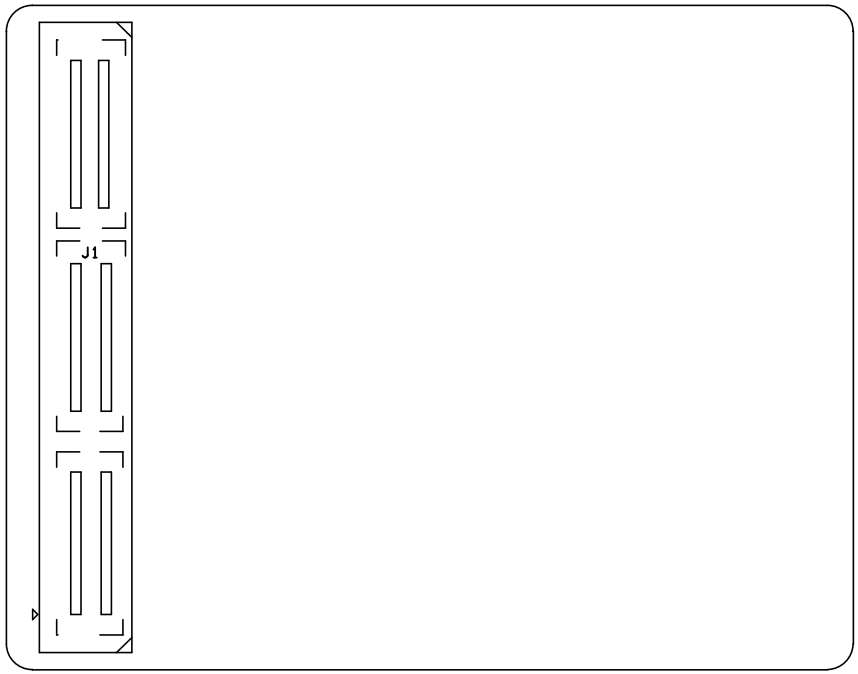
REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
1	INITIAL RELEASE	11/04/14	
2	NETNAME CHANGE DELETION OF TWO MOUNTING HOLES	15/05/14	
3	FIXED DFA ISSUES	05/06/14	



620-60201-01 HSMC ICB REV03 SECONDARY ASSEMBLY BOTTOM

UNLESS OTHERWISE SPECIFIED	SIGNATURES	DATE
DIMENSIONS ARE IN INCHES(MM) TOLERANCES ON: ANGLES +/- 2° 2 PL DECIMALS +/- .010 3 PL DECIMALS +/- .005 THIRD ANGLE PROJECTIONS	DRAWN : SRIRAMAN	05/06/14
	CHECKED : PRAJITH	05/06/14
	ENGRG : SHREESHA	05/06/14
	ISSUED	

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198 CHAMPION COURT
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(408) 943-2600

ASSEMBLY BOTTOM
CYUSB3ACC-006
HSMC INTERCONNECT BOARD

SIZE	FSCM NO	DWG NO	REV
C		620-60201-01	03

SCALE: 1/1 SHEET: 1 OF 1